



Integrated Device Technology, Inc.
6024 Silver Creek Valley Road, San Jose, CA 95138

PRODUCT/PROCESS CHANGE NOTICE (PCN)

PCN #: **K1208-01R1** DATE: **October 10, 2012**
 Product Affected: 9FG104C
 9FG104D
 9FG108C
 9FG108D
 Date Effective: **December 11, 2012**

MEANS OF DISTINGUISHING CHANGED DEVICES:
 Product Mark New Ordering Part#
 Back Mark
 Date Code
 Other

Contact: Bimla Paul
 Title: Product Quality Assurance Attachment: Yes No
 Phone #: (408) 574-6419
 Fax #: (408) 284-8362 Samples: Contact your local sales representative for
 E-mail: Bimla.Paul@idt.com sample and datasheet requests.

DESCRIPTION AND PURPOSE OF CHANGE:

- Die Technology
- Wafer Fabrication Process
- Assembly Process
- Equipment
- Material
- Testing
- Manufacturing Site
- Data Sheet
- Other - Die revision (New Ordering Part#)

Revision 1: This revised notification is to advise customers of the last time buy date for "C" and "D" die revision is September 11, 2013 with last ship date of December 11, 2013.

This notification is to advise our customers that IDT has made a metal-layer only die revision to the devices mentioned above. This die revision improves production yield of the devices. IDT will be discontinuing the Rev C and Rev D devices and is asking customers to qualify the Rev E devices and switch to this revision. Rev E has the same performance as Rev D and much improved performance over the Rev C. The orderable part numbers have changed to indicate the Rev E.

RELIABILITY/QUALIFICATION SUMMARY:

There is no expected change to the product quality or reliability performance.

CUSTOMER ACKNOWLEDGMENT OF RECEIPT:

IDT records indicate that you require written notification of this change. Please use the acknowledgement below or E-Mail to grant approval or request additional information. If IDT does not receive acknowledgement within 30 days of this notice it will be assumed that this change is acceptable.
 IDT reserves the right to ship either version manufactured after the process change effective date until the inventory on the earlier version has been depleted.

Customer: _____ *Approval for shipments prior to effective date.*
 Name/Date: _____ E-Mail Address: _____
 Title: _____ Phone # /Fax #: _____

CUSTOMER COMMENTS: _____

IDT ACKNOWLEDGMENT OF RECEIPT:

RECD. BY: _____ DATE: _____



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ATTACHMENT I - PCN #: K1208-01R1

PCN Type: Die Revision Change

Data Sheet Change: Yes

Detail of Change:

This notification is to advise our customers that IDT has made a metal-layer only die revision to the devices mentioned above. This die revision improves production yield of the devices. IDT will be discontinuing the Rev C and Rev D devices and is asking customers to qualify the Rev E devices and switch to this revision. Rev E has the same performance as Rev D and much improved performance over the Rev C. The orderable part numbers have changed to indicate the Rev E as shown in Table 1.

Table 1

| Existing Ordering Part# | New Ordering Part# |
|-------------------------|--------------------|
| 9FG104CFLF | 9FG104EFLF |
| 9FG104CFLFT | 9FG104EFLFT |
| 9FG104CGLF | 9FG104EGLF |
| 9FG104CGLFT | 9FG104EGLFT |
| 9FG104DFILF | 9FG104EFILF |
| 9FG104DFILFT | 9FG104EFILFT |
| 9FG104DFLF | 9FG104EFLF |
| 9FG104DFLFT | 9FG104EFLFT |
| 9FG104DGILF | 9FG104EGILF |
| 9FG104DGILFT | 9FG104EGILFT |
| 9FG104DGLF | 9FG104EGLF |
| 9FG104DGLFT | 9FG104EGLFT |
| 9FG108CFLF | 9FG108EFLF |
| 9FG108CFLFT | 9FG108EFLFT |
| 9FG108CGLF | 9FG108EGLF |
| 9FG108CGLFT | 9FG108EGLFT |
| 9FG108DFILF | 9FG108EFILF |
| 9FG108DFILFT | 9FG108EFILFT |
| 9FG108DFLF | 9FG108EFLF |
| 9FG108DFLFT | 9FG108EFLFT |
| 9FG108DGILF | 9FG108EGILF |
| 9FG108DGILFT | 9FG108EGILFT |
| 9FG108DGLF | 9FG108EGLF |
| 9FG108DGLFT | 9FG108EGLFT |

There is no change in die technology/process. Samples are available for customer evaluation upon request.



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PRODUCT/PROCESS CHANGE NOTICE (PCN)

ATTACHMENT I - PCN #: K1208-01R1

Qualification Test Plan and Result:

Product: 9FG108EGILF

Foundry: Global Foundries

Technology Information: CMOS 0.35 μ m

Report Date: June 12, 2012

Device Qual Test Results Summary

| Test Description | Conditions | Sample Size | Rejects | Comments |
|-----------------------------|---------------|-------------|---------|----------|
| ESD: Human Body Model | JS-001 | 3 | 0 | 2000V |
| ESD: Charged Device Model | JESD22-C101 | 3 | 0 | 500V |
| Latch-Up | JESD78 | 6 | 0 | |
| Electrical Characterization | Per Datasheet | 10* | - | Passed |

Note: * Sample size applies to base characterization

Qualification Test Result Summary – JESD47 Recommended Tests

| Test /Conditions | Conditions | Sample Size | Rejects | Comments |
|---|---|-------------|---------|----------|
| High Temperature Operating Life (Dynamic) | JESD22-A108D, +125°C, Vccmax @ 1000 hours or equivalent | 77 | 0 | |
| | | 77 | 0 | |
| | | 77 | 0 | |
| Temperature Cycle | JESD22-A104D, -55°C to +125°C, 700 cycles | 25 | 0 | |
| | | 25 | 0 | |
| | | 25 | 0 | |
| High Temperature Storage Bake | JESD22-A-103D, 150°C, 1000 hrs | 25 | 0 | |
| | | 25 | 0 | |
| | | 25 | 0 | |
| Highly Accelerated Stress Test (HAST) | EIA/JESD22-A110D, 130°C/85%R.H. Vcc max for 100 hours. | 25 | 0 | |
| | | 25 | 0 | |
| | | 25 | 0 | |
| Ball Shear Test | JESD22-B116A, Ball Shear Strength | 5 | 0 | |

Note: For HAST and Temperature Cycle, samples have been subjected to pre-conditioning per JESD22-A113